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10/779,563 **Application Number** TRANSMITTAL Filing Date February 16, 2004 **FORM** First Named Inventor Yoshiro Iwasa (to be used for all correspondence after initial filing) Art Unit 2826 **Examiner Name** Alexander O. Williams

Total Number of Pages in This Submission Attorney Docket Number 9319S-000666 ENCLOSURES (check all that apply) After Allowance Communication to Fee Transmittal Form □ Drawing(s) Technology Center (TC) Appeal Communication to Board of Fee Attached Licensing-related Papers Appeals and Interferences Petition Appeal Communication to TC Amendment / Reply (Appeal Notice, Brief, Reply Brief) Petition to Convert to a Proprietary Information After Final Provisional Application Power of Attorney, Revocation Status Letter Affidavits/declaration(s) Change of Correspondence Address Terminal Disclaimer Other Enclosure(s) Extension of Time Request (please identify below): Return Receipt Postcard Request for Refund Express Abandonment Request CD, Number of CD(s) Information Disclosure Statement The Commissioner is hereby authorized to charge any additional Remarks Certified Copy of Priority fees that may be required under 37 CFR 1.16 or 1.17 to Deposit Document(s) Account No. 50-3213. A duplicate copy of this sheet is enclosed. Response to Missing Parts/ Incomplete Application Response to Missing Parts under 37 CFR 1.52 or 1.53 SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT Attorney Name Reg. No. Firm G. Gregory Schivley 27,382 / 40,344 Harness, Dickey & Pierce, P.L.C. Bryan E. Wade Individual name Signature December 19, 2005 Date

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Group Art Unit:

2826

Examiner:

Applicant:

Alexander O. Williams

Title:

LEAD FRAME FOR ACCOMMODATING SEMICONDUCTOR

CHIPS OF VARIOUS DIFFERENT SIZES

Attorney Docket:

9319S-000666

Yoshiro Iwasa

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

## <u>AMENDMENT</u>

Sir:

In response to the Office Action mailed September 22, 2005, please amend the application as follows and consider the remarks set forth below.

Amendments to the Title begin on page 2 of this paper.

Amendments to the Claims begin on page 3 of this paper.

Remarks begin on page 5 of this paper.

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## **AMENDMENTS TO THE TITLE**

Please amend the title as rewritten in amendment format.

LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

<u>LEAD FRAME FOR ACCOMMODATING SEMICONDUCTOR CHIPS OF VARIOUS DIFFERENT SIZES</u>